

L Number	Hits	Search Text	DB	Time stamp
1	0	duplexer same advan\$4	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 15:55
3	4	(duplexer same advan\$4) and (wireless adj system)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 15:56
2	448	duplexer same advan\$4	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:03
4	2	("5578525").PN.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:08
5	14	("4233620"   "4264917"   "4633573"   "4721945"   "4769272"   "4835120"   "4901136"   "5102829"   "5206188"   "5309021"   "5342807"   "5357400"   "5474957"   "5519936").PN.	USPAT	2003/12/13 16:04
6	23	5578525.URPN.	USPAT	2003/12/13 16:09
7	0	(437/206).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:08
8	0	(437/206).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:09
9	1021	(257/704).CCLS.	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:24
10	8859	solder adj ball	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:28
11	8437	solder adj paste	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:28
12	1033	(solder adj ball) and (solder adj paste)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:34
13	167195	PCB or (printed adj circuit adj board)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
14	3525645	(PCB or (printed adj circuit adj board)) ad opening	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
15	167195	(PCB or (printed adj circuit adj board)) and ((PCB or (printed adj circuit adj board)) ad opening)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
16	697	((solder adj ball) and (solder adj paste)) and ((PCB or (printed adj circuit adj board)) ad opening)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:30
17	245	((solder adj ball) and (solder adj paste)) and ((PCB or (printed adj circuit adj board)) ad opening)) and carrier	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:41

18	1983	signal adj trace	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:42
19	834	signal adj skew	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:42
20	7	(signal adj trace) and (signal adj skew)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:45
21	2	("5983493"   "6194778").PN.	USPAT	2003/12/13 16:44
22	138656	multilayer	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:45
23	3048	multilayer adj substrate	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:46
24	2	(multilayer adj substrate) and (signal adj skew)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:47
25	16	multilayer and (signal adj skew)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 16:47
26	32	("3930857"   "4604644"   "4814943"   "5121190"   "5128746"   "5136365"   "5194930"   "5216278"   "5218234"   "5227008"   "5261155"   "5355283"   "5357673"   "5371404"   "5398863"   "5401913"   "5436503"   "5442240"   "5450283"   "5489749"   "5536909"   "5550408"   "5583376"   "5583378"   "5601678"   "5647123"   "5650593"   "5663530"   "5686703"   "5717252"   "5744863"   "5801449").PN.	USPAT	2003/12/13 16:55
27	155	((solder adj ball) and (solder adj paste)) and (melting adj temperature)	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:34
28	16	174/250-268.ccls. and (((solder adj ball) and (solder adj paste)) and (melting adj temperature))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:37
29	17	361/760-795.ccls. and (((solder adj ball) and (solder adj paste)) and (melting adj temperature))	USPAT; EPO; JPO; DERWENT; USOCR	2003/12/13 17:37
30	12	("4882454"   "5072075"   "5121190"   "5483421"   "5574630"   "5615087"   "5661089"   "5798563"   "5894173"   "5900675"   "5926377"   "5982630").PN.	USPAT	2003/12/13 17:37